



TTTC News

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PAST TTTC EVENTS

The 21st Design, Automation, and Test in Europe (DATE) Conference

19–23 March 2018

Dresden, Germany

<https://www.date-conference.com/>

The 21st DATE conference and exhibition is the main European event bringing together designers and design automation users, researchers and vendors, as well as specialists in the hardware and software design, test and manufacturing of electronic circuits and systems. DATE emphasizes on both technology and systems, covering integrated circuits (ICs)/system-on-chips (SoCs), reconfigurable hardware and embedded systems, and embedded software.

The five-day event consists of a conference with plenary invited papers, regular papers, panels, hot-topic sessions, tutorials, and workshops, two special focus days and a track for executives. The scientific conference is complemented by a commercial exhibition showing the state of the art in design and test tools, methodologies, IP, and design services, reconfigurable and other hardware platforms, embedded software, and (industrial) design experiences from different application domains, e.g., automotive, wireless, telecom, and multimedia applications. The organization of user group meetings, fringe meetings, a university booth, a PhD forum, vendor presentations, and social events offers a wide variety of extra opportunities to meet and exchange information on relevant issues for the design and test community. Special space will also be allocated for EU-funded projects to show their results.

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The IEEE VLSI Test Symposium

22–25 April 2018

San Francisco, CA, USA

http://ttcc-vts.org/public_html/new/2018/

The IEEE VLSI Test Symposium (VTS) explores emerging trends and novel concepts in testing, debug, and repair of microelectronic circuits and systems. The VTS Program consists of technical papers and special sessions, focused on analog/mixed-signal/RF test, ATPG and compression, pre and post silicon debug, automotive test and safety, built-in self-test, defect and current-based test, defect/fault tolerance, delay and performance test, design for resiliency, design for testability, design verification/validation, diagnosis and debug, embedded system and board test, embedded test methods, emerging technologies test, fault modeling and simulation, hardware security and trust, low-power IC test, microsystems/MEMS/sensors test, memory test and repair, online test and error correction, power/thermal issues in test, reconfigurable system test, reliability evaluation, SoC test, test standards, test economics, test of biomedical devices, test of high-speed I/O, test quality and reliability, test resource partitioning, transients and soft errors, and 2.5 D, 3 D, and SiP test.

The IEEE International Symposium on Design and Diagnostics of Electronic Circuits and Systems (DDECS 2018)

25–27 April 2018

Budapest, Hungary

<https://ddecs2018.itk.ppke.hu/>

The IEEE International Symposium on Design and Diagnostics of Electronic Circuits and Systems provides a forum for exchanging ideas, discussing research results, and presenting practical applications in the areas of design, test, and diagnosis of electronic circuits and systems.

Prospective authors are cordially invited to submit original papers to the Symposium. Papers in English

with a length of six pages maximum in a standard IEEE conference style are expected. Specialized student and industrial sessions, as well as embedded tutorials, will be organized at the symposium. Accepted papers will be included in the Symposium Proceedings and submitted for inclusion into IEEE *Xplore* as well as other Abstracting and Indexing databases (WoS, Scopus, etc). An extra work-in-progress session will be targeted to get early feedback on in-progress research and preliminary results (these papers will not be included in IEEE *Xplore*).

UPCOMING TTTC EVENTS

The 23rd IEEE European Test Symposium (ETS'18)

28 May–1 June 2018

Bremen, Germany

<http://www.informatik.uni-bremen.de/ets18/>

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, applications, hot topics, and new trends in the area of electronic-based circuit and system testing and reliability. In 2018, ETS will take place at Swissôtel, Bremen, Germany. It is organized by the University of Bremen, which co-sponsors the event jointly with the IEEE Council on Electronic Design Automation. ETS traditionally enjoys a strong balance among academic and industrial participants. In addition to regular Scientific Papers, Special Sessions, Panels, and Embedded Tutorials, ETS features Vendor Sessions

and Table-Top Demos as well as a special track on Emerging Test Strategies (ETS²) where new issues are presented by the industry and are discussed in an informal atmosphere. ETS is the major event of the European Test Week, which includes Test Spring School and fringe workshops.

NEWSLETTER EDITOR'S INVITATION

I would appreciate input and suggestions about the newsletter from the test community. Please forward your ideas, contributions, and information on awards, conferences, and workshops to Theocharis (Theo) Theocharides, Department of Electrical and Computer Engineering, University of Cyprus, 75 Kallipoleos Avenue, PO Box 20537, Nicosia 1678, Cyprus; ttheocharides@ucy.ac.cy.

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